Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	12 X 12 X 0.80 (5.1 EP)
Lead Count	88
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.54E-01	86.91	869100	33.74	337429
Thermosets	Epoxy & Phenol Resin	Proprietary	2.26E-02	12.78	127800	4.96	49618
Other inorganic materials	Carbon black	1333-86-4	5.48E-04	0.31	3100	0.12	1204
Subtotal			1.77E-01	100.00	1000000	38.83	388251

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.50 E-01	96.20	962000	54.89	548881
Copper & its alloys	Nickel	7440-02-0	7.80 E-03	3.00	30000	1.71	17117
Copper & its alloys	Silicon	7440-21-3	1.69 E-03	0.65	6500	0.37	3709
Copper & its alloys	Magnesium	7439-95-4	3.90 E-04	0.15	1500	0.09	856
Subtotal			2.60 E-01	100.00	1000000	57.06	570562

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.60 E-04	100.0	1000000	0.06	571

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.84 E-03	100.0	1000000	0.62	6235

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.30 E-03	100.0	1000000	0.51	5052

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.15 E-02	100.0	1000000	2.53	25344

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.33 E-03	73.54	735400	0.29	2931
Other organic materials	Epoxy resin A	TS ref# 10013	1.33 E-04	7.35	73500	0.03	293
Others	Anhydride	TS ref# 10181	1.33 E-04	7.35	73500	0.03	293
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	5.34 E-05	2.94	29400	0.01	117
Other organic materials	Epoxy resin B	TS ref# 10237	5.34 E-05	2.94	29400	0.01	117
Others	Epoxy resin modifier	TS ref# 10038	5.34 E-05	2.94	29400	0.01	117
Others	Anhydride	TS ref# 10180	5.34 E-05	2.94	29400	0.01	117
Subtotal			1.82 E-03	100.0	1000000	0.40	3985

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.56 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary